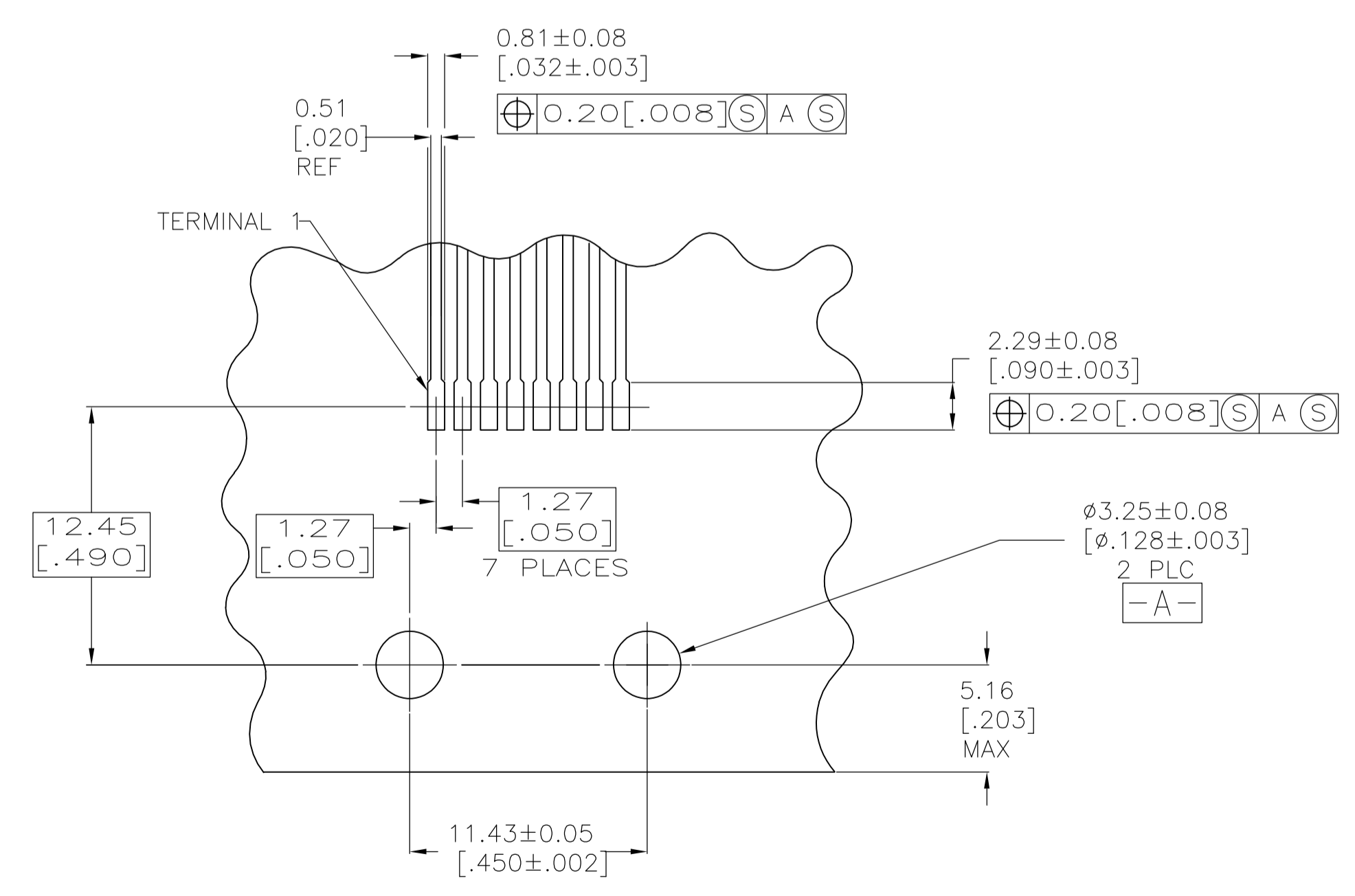
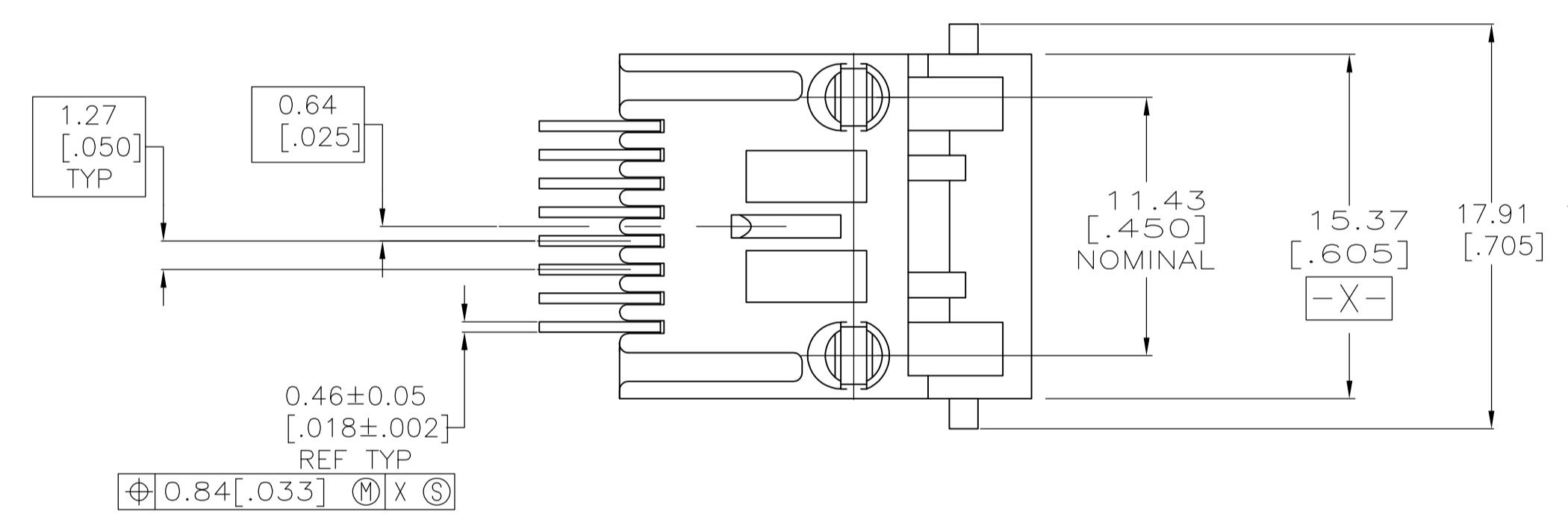
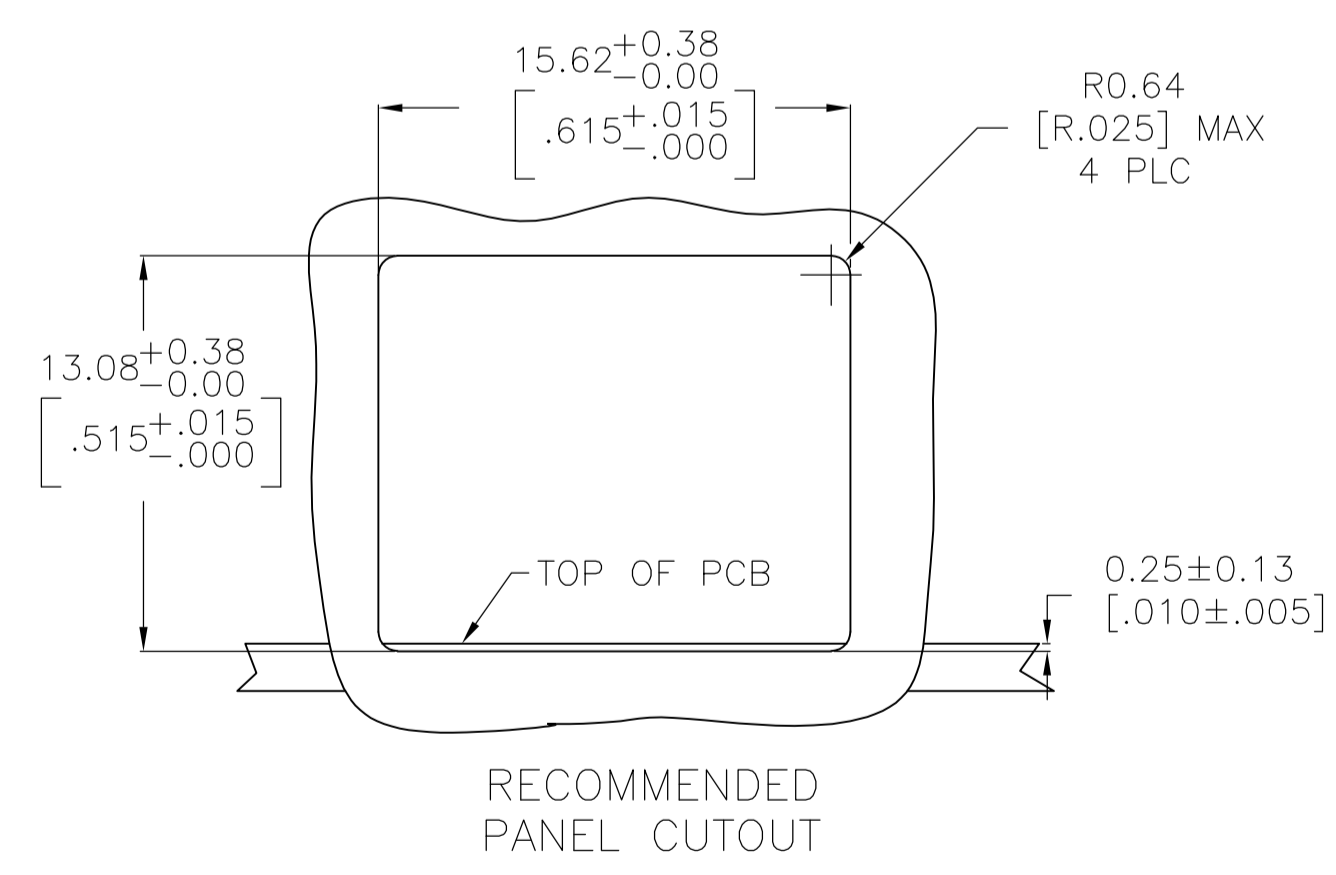


1. MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 VO, COLOR: BLACK.
 TERMINAL - 0.36 [.014] THICK PHOS-BRONZE PLATE WITH 1.27μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
2. CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
4. SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE



RECOMMENDED PANEL CUTOUT

8	5555078-1
NUMBER OF TERMINALS	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G. ATTADIA - 07/JUN/2005		Tyco Electronics Corporation	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 07/JUN/2005		Tyco Electronics Corporation Harrisburg, PA 17105-3608	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 07/JUN/2005		NAME	
0 PLC ± -		PRODUCT SPEC		MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT, KEYED, WITH PANEL STOPS	
1 PLC ± -		APPLICATION SPEC		108-1163	
2 PLC ± -		SIZE		114-6040	
3 PLC ± -		CAGE CODE		DRAWING NO	
4 PLC ± -		WEIGHT		RESTRICTED TO	
ANGLES ± -		CUSTOMER DRAWING		SCALE 4:1 SHEET 1 OF 1 REV B	